

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$	$I_D$ $T_A = +25^\circ\text{C}$
-100V	350m $\Omega$ @ $V_{GS} = -10\text{V}$	-2.4A
	450m $\Omega$ @ $V_{GS} = -6\text{V}$	-2.1A

## Description and Applications

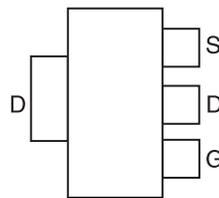
This MOSFET is designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor Control
- DC-DC Converters
- Power Management Functions
- Relay and Solenoid Driving

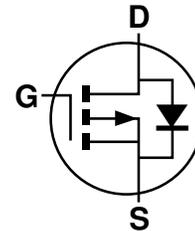
SOT223



Top View



Pin Out - Top



Equivalent Circuit

## Features and Benefits

- Fast Switching Speed
- Low Input Capacitance
- Low Gate Drive
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

## Mechanical Data

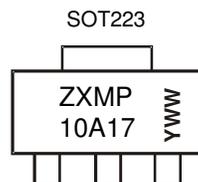
- Case: SOT223
- Case Material: Molded Plastic; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 <sup>Ⓔ</sup>
- Weight: 0.112 grams (Approximate)

## Ordering Information (Note 4)

Product	Case	Packaging
ZXMP10A17GTA	SOT223	1,000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



ZXMP 10A17 = Product Type Marking Code  
 YWW = Date Code Marking  
 Y or  $\bar{Y}$  = Last Digit of Year (ex: 5= 2015)  
 WW or  $\bar{W}W$  = Week Code (01~53)

**Maximum Ratings** (@T<sub>A</sub> = +25°C unless otherwise specified.)

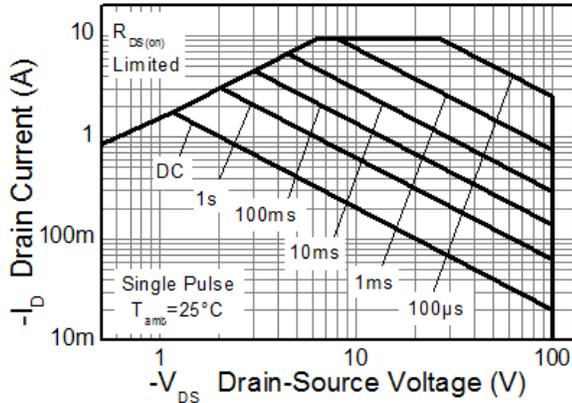
Characteristic			Symbol	Value	Unit	
Drain-Source Voltage			V <sub>DSS</sub>	-100	V	
Gate-Source Voltage			V <sub>GS</sub>	±20	V	
Continuous Drain Current	V <sub>GS</sub> = 10V	(Note 6)	I <sub>D</sub>	-2.4	A	
		T <sub>A</sub> = +70°C (Note 6)		-1.9		
		(Note 5)		-1.7		
Pulsed Drain Current	V <sub>GS</sub> = 10V	(Note 7)	I <sub>DM</sub>	-9.4	A	
Continuous Source Current (Body Diode)			(Note 6)	I <sub>S</sub>	-4.5	A
Pulsed Source Current (Body Diode)			(Note 7)	I <sub>SM</sub>	-9.4	A

**Thermal Characteristics** (@T<sub>A</sub> = +25°C unless otherwise specified.)

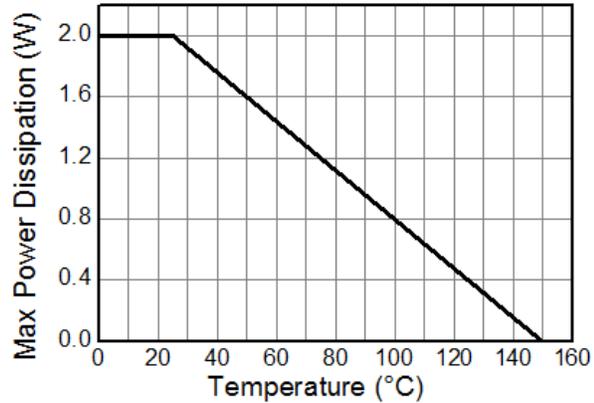
Characteristic		Symbol	Value	Unit
Power Dissipation Linear Derating Factor	(Note 5)	P <sub>D</sub>	2.0	W mW/°C
			16	
	(Note 6)		3.9 31	
Thermal Resistance, Junction to Ambient	(Note 5)	R <sub>θJA</sub>	62.5	°C/W
	(Note 6)		32.0	
Thermal Resistance, Junction to Case	(Note 8)	R <sub>θJL</sub>	9.8	
Operating and storage temperature range		T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C

- Notes:
5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
  6. Same as Note 5, except the device is measured at t ≤ 10 seconds.
  7. Same as Note 5, except the device is pulsed with D= 0.02 and pulse width 300 μs. The pulse current is limited by the maximum junction temperature.
  8. Thermal resistance from junction to solder-point (at the end of the drain lead).

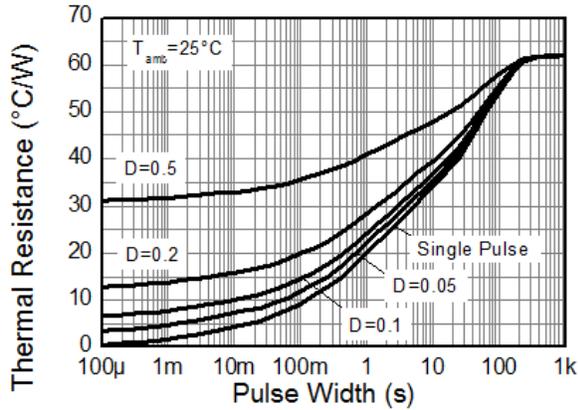
**Thermal Characteristics**



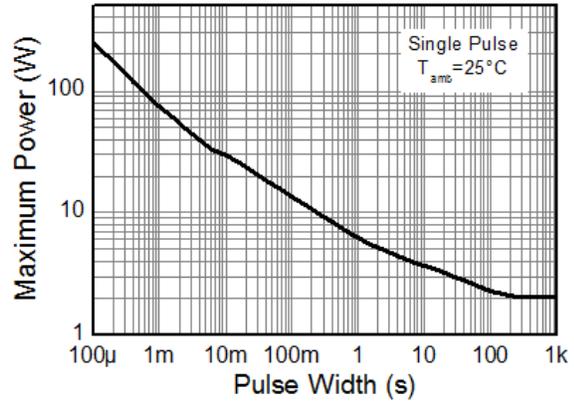
**Safe Operating Area**



**Derating Curve**



**Transient Thermal Impedance**



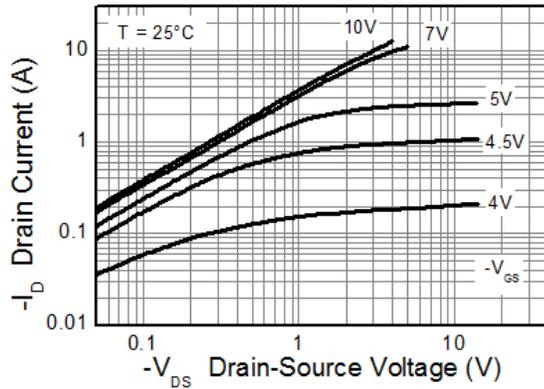
**Pulse Power Dissipation**

**Electrical Characteristics** (@T<sub>A</sub> = +25 °C unless otherwise specified.)

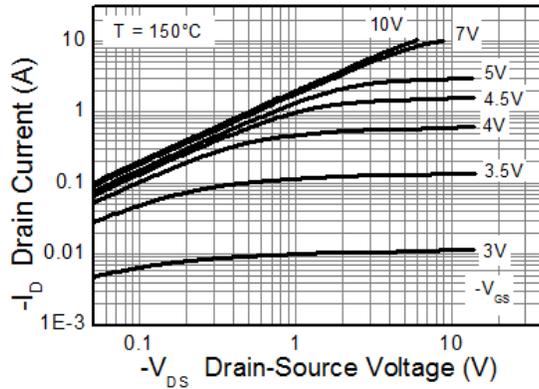
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-100	—	—	V	I <sub>D</sub> = -250μA, V <sub>GS</sub> = 0V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	-0.5	μA	V <sub>DS</sub> = -100V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	-2.0	—	-4.0	V	I <sub>D</sub> = -250μA, V <sub>DS</sub> = V <sub>GS</sub>
Static Drain-Source On-Resistance (Note 9)	R <sub>DS(on)</sub>	—	—	0.350	Ω	V <sub>GS</sub> = -10V, I <sub>D</sub> = -1.4A
				0.450		V <sub>GS</sub> = -6V, I <sub>D</sub> = -1.2A
Forward Transconductance (Notes 9 & 10)	g <sub>fs</sub>	—	2.8	—	S	V <sub>DS</sub> = -15V, I <sub>D</sub> = -1.4A
Diode Forward Voltage (Note 9)	V <sub>SD</sub>	—	-0.85	-0.95	V	I <sub>S</sub> = -1.7A, V <sub>GS</sub> = 0V
Reverse Recovery Time (Note 10)	t <sub>rr</sub>	—	33	—	ns	I <sub>F</sub> = -1.5A, di/dt = 100A/μs
Reverse Recovery Charge (Note 10)	Q <sub>rr</sub>	—	48	—	nC	
<b>DYNAMIC CHARACTERISTICS (Note 10)</b>						
Input Capacitance	C <sub>iSS</sub>	—	424	—	pF	V <sub>DS</sub> = -50V, V <sub>GS</sub> = 0V f = 1MHz
Output Capacitance	C <sub>oss</sub>	—	36.6	—	pF	
Reverse Transfer Capacitance	C <sub>rSS</sub>	—	29.8	—	pF	
Total Gate Charge (Note 11)	Q <sub>g</sub>	—	7.1	—	nC	V <sub>GS</sub> = -6.0V
Total Gate Charge (Note 11)	Q <sub>g</sub>	—	10.7	—	nC	V <sub>GS</sub> = -10V
Gate-Source Charge (Note 11)	Q <sub>gs</sub>	—	1.7	—	nC	
Gate-Drain Charge (Note 11)	Q <sub>gd</sub>	—	3.8	—	nC	
Turn-On Delay Time (Note 11)	t <sub>D(on)</sub>	—	3.0	—	ns	V <sub>DD</sub> = -15V, V <sub>GS</sub> = -10V I <sub>D</sub> = -1A, R <sub>G</sub> ≅ 6.0Ω
Turn-On Rise Time (Note 11)	t <sub>r</sub>	—	3.5	—	ns	
Turn-Off Delay Time (Note 11)	t <sub>D(off)</sub>	—	13.4	—	ns	
Turn-Off Fall Time (Note 11)	t <sub>f</sub>	—	7.2	—	ns	

Notes: 9. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%.  
10. For design aid only, not subject to production testing.  
11. Switching characteristics are independent of operating junction temperatures.

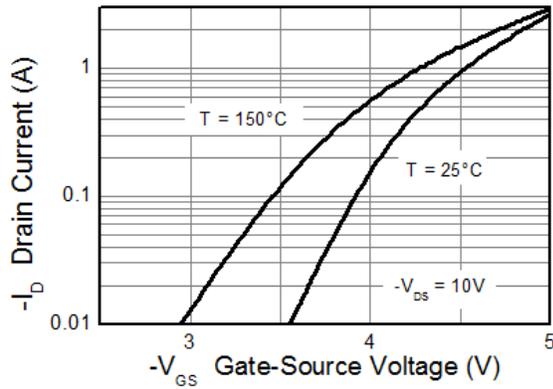
**Typical Characteristics**



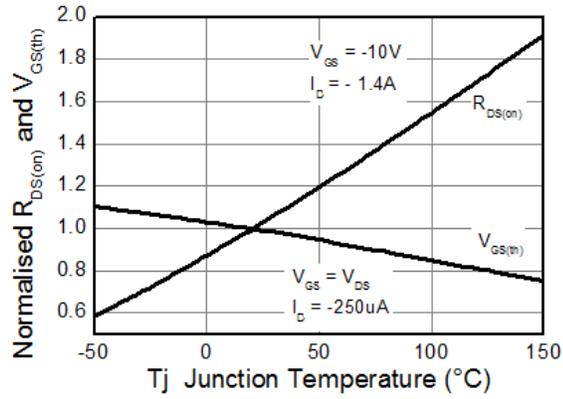
**Output Characteristics**



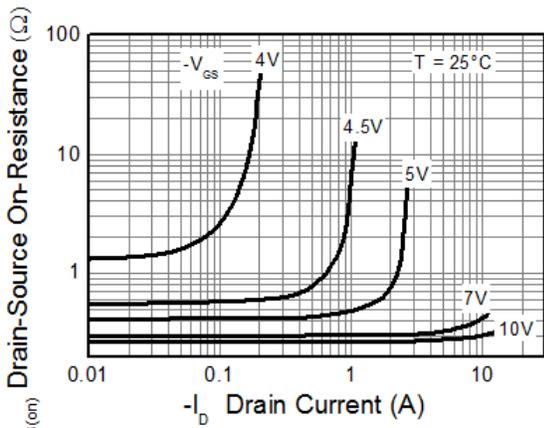
**Output Characteristics**



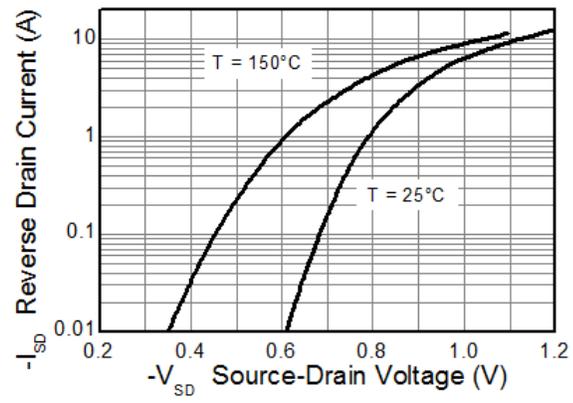
**Typical Transfer Characteristics**



**Normalised Curves v Temperature**

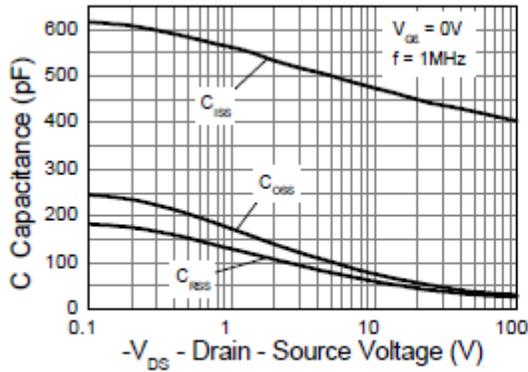


**On-Resistance v Drain Current**

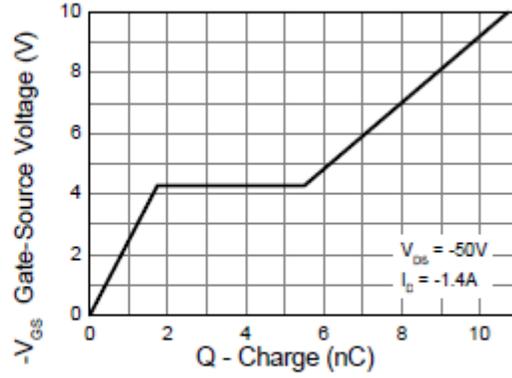


**Source-Drain Diode Forward Voltage**

**Typical Characteristics (cont.)**

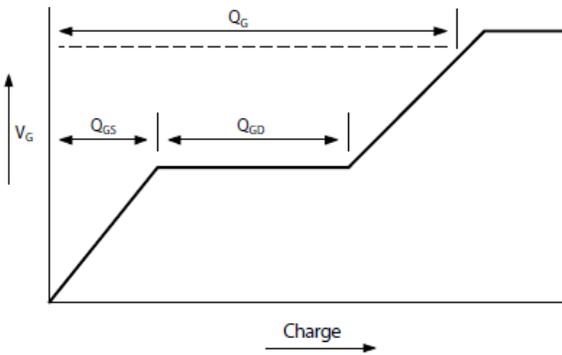


**Capacitance v Drain-Source Voltage**

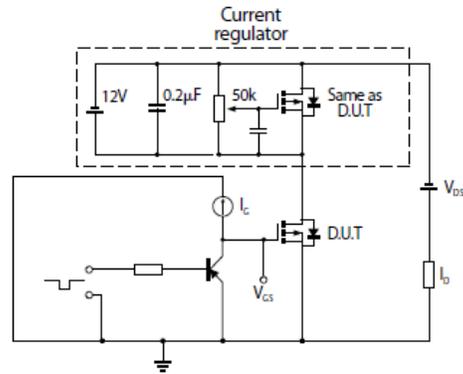


**Gate-Source Voltage v Gate Charge**

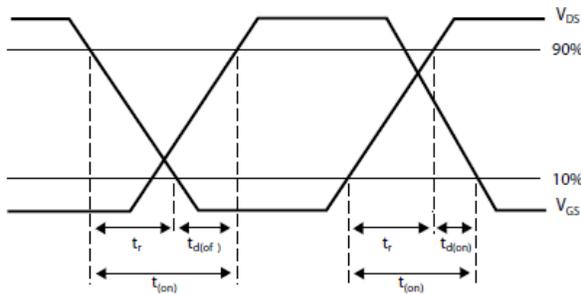
**Test Circuits**



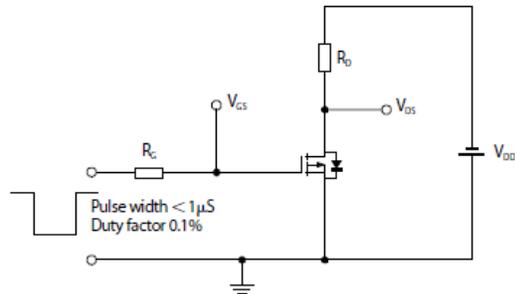
**Basic gate charge waveform**



**Gate charge test circuit**



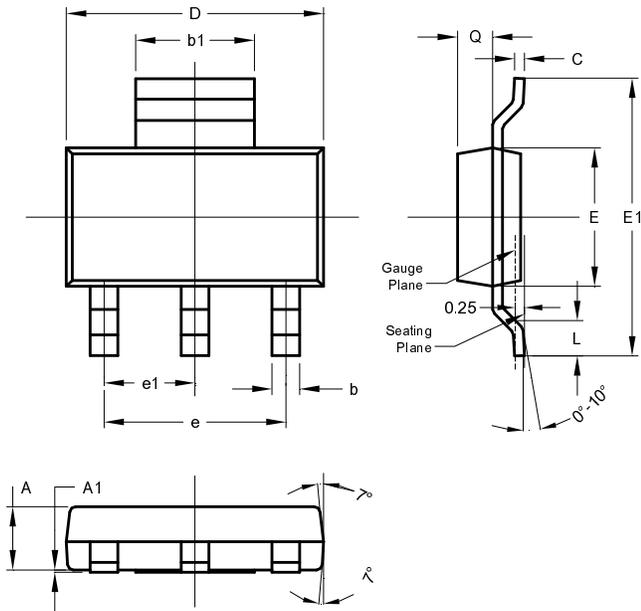
**Switching time waveforms**



**Switching time test circuit**

**Package Outline Dimensions**

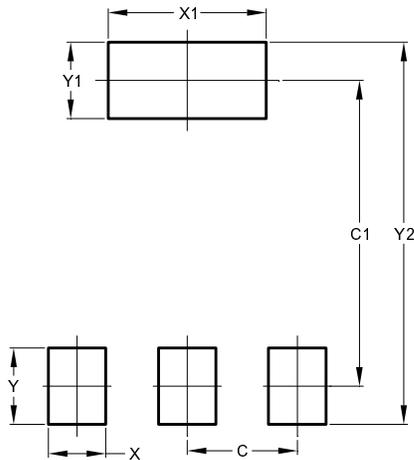
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

**Suggested Pad Layout**

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00

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